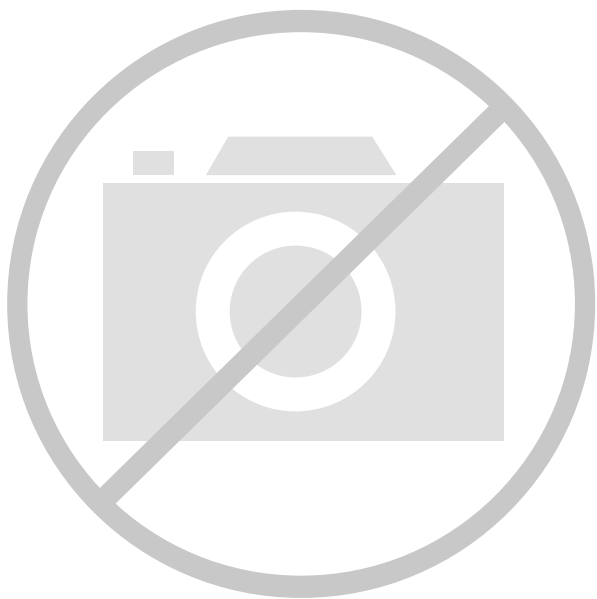




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The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	2016
Number of Logic Elements/Cells	-
Total RAM Bits	18432
Number of I/O	168
Number of Gates	125000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Package / Case	324-BGA
Supplier Device Package	324-FBGA (19x19)
Purchase URL	https://www.e-xfl.com/product-detail/microsemi/ax125-2fg324i

User I/Os²

Introduction

The Axcelerator family features a flexible I/O structure, supporting a range of mixed voltages (1.5 V, 1.8 V, 2.5 V, and 3.3 V) with its bank-selectable I/Os. Table 2-8 on page 2-12 contains the I/O standards supported by the Axcelerator family, and Table 2-10 on page 2-12 compares the features of the different I/O standards.

Each I/O provides programmable slew rates, drive strengths, and weak pull-up and weak pull-down circuits. The slew rate setting is effective for both rising and falling edges.

I/O standards, except 3.3 V PCI and 3.3 V PCI-X, are capable of hot insertion. 3.3 V PCI and 3.3 V PCI-X are 5 V tolerant with the aid of an external resistor.

The input buffer has an optional user-configurable delay element. The element can reduce or eliminate the hold time requirement for input signals registered within the I/O cell. The value for the delay is set on a bank-wide basis. Note that the delay WILL be a function of process variations as well as temperature and voltage changes.

Each I/O includes three registers: an input (InReg), an output (OutReg), and an enable register (EnReg). I/Os are organized into banks, and there are eight banks per device—two per side (Figure 2-6 on page 2-18). Each I/O bank has a common VCCI, the supply voltage for its I/Os.

For voltage-referenced I/Os, each bank also has a common reference-voltage bus, VREF. While VREF must have a common voltage for an entire I/O bank, its location is user-selectable. In other words, any user I/O in the bank can be selected to be a VREF.

The location of the VREF pin should be selected according to the following rules:

- Any pin that is assigned as a VREF can control a maximum of eight user I/O pad locations in each direction (16 total maximum) within the same I/O bank.
- I/O pad locations listed as no connects are counted as part of the 16 maximum. In many cases, this leads to fewer than eight user I/O package pins in each direction being controlled by a VREF pin.
- Dedicated I/O pins such as GND and VCCI are counted as part of the 16.
- The two user I/O pads immediately adjacent on each side of the VREF pin (four in total) may only be used as inputs. The exception is when there is a VCCI/GND pair separating the VREF pin and the user I/O pad location.
- The user does not need to assign VREF pins for OUTBUF and TRIBUF. VREF pins are needed only for input and bidirectional I/Os.

The differential amplifier supply voltage VCCDA should be connected to 3.3 V.

A user can gain access to the various I/O standards in three ways:

- Instantiate specific library macros that represent the desired specific standard.
- Use generic I/O macros and then use Designer's PinEditor to specify the desired I/O standards (please note that this is not applicable to differential standards).
- A combination of the first two methods.

Refer to the *I/O Features in Axcelerator Family Devices* application note and the *Antifuse Macro Library Guide* for more details.

2. Do not use an external resistor to pull the I/O above V_{CCI} for a higher logic "1" voltage level. The desired higher logic "1" voltage level will be degraded due to a small I/O current, which exists when the I/O is pulled up above V_{CCI} .

Using the Weak Pull-Up and Pull-Down Circuits

Each Axcelerator I/O comes with a weak pull-up/down circuit (on the order of 10 k Ω). These are weak transistors with the gates tied on, so the on resistance of the transistor emulates a resistor. The weak pull-up and pull-down is active only when the device is powered up, and they must be biased to be on. When the rails are coming up, they are not biased fully, so they do not behave as resistors until the voltage is at sufficient levels to bias the transistors. The key is they really are transistors; they are not traces of poly silicon, which is another way to do an on-chip resistor (those take much more room). I/O macros are provided for combinations of pull up/down for LVTTL, LVCMOS (2.5 V, 1.8 V, and 1.5 V) standards. These macros can be instantiated if a keeper circuit for any input buffer is required.

Customizing the I/O

- A five-bit programmable input delay element is associated with each I/O. The value of this delay is set on a bank-wide basis (Table 2-14). It is optional for each input buffer within the bank (i.e. the user can enable or disable the delay element for the I/O). When the input buffer drives a register within the I/O, the delay element is activated by default to ensure a zero hold-time. The default setting for this property can be set in Designer. When the input buffer does not drive a register, the delay element is deactivated to provide higher performance. Again, this can be overridden by changing the default setting for this property in Designer.
- The slew-rate value for the LVTTL output buffer can be programmed and can be set to either slow or fast.
- The drive strength value for LVTTL output buffers can be programmed as well. There are four different drive strength values – 8 mA, 12 mA, 16 mA, or 24 mA – that can be specified in Designer.⁵

Table 2-14 • Bank-Wide Delay Values

Bits Setting	Delay (ns)	Bits Setting	Delay (ns)
0	0.54	16	2.01
1	0.65	17	2.13
2	0.71	18	2.19
3	0.83	19	2.3
4	0.9	20	2.38
5	1.01	21	2.49
6	1.08	22	2.55
7	1.19	23	2.67
8	1.27	24	2.75
9	1.39	25	2.87
10	1.45	26	2.93
11	1.56	27	3.04
12	1.64	28	3.12
13	1.75	29	3.23
14	1.81	30	3.29
15	1.93	31	3.41

Note: Delay values are approximate and will vary with process, temperature, and voltage.

5. These values are minimum drive strengths.

I/O Module Timing Characteristics

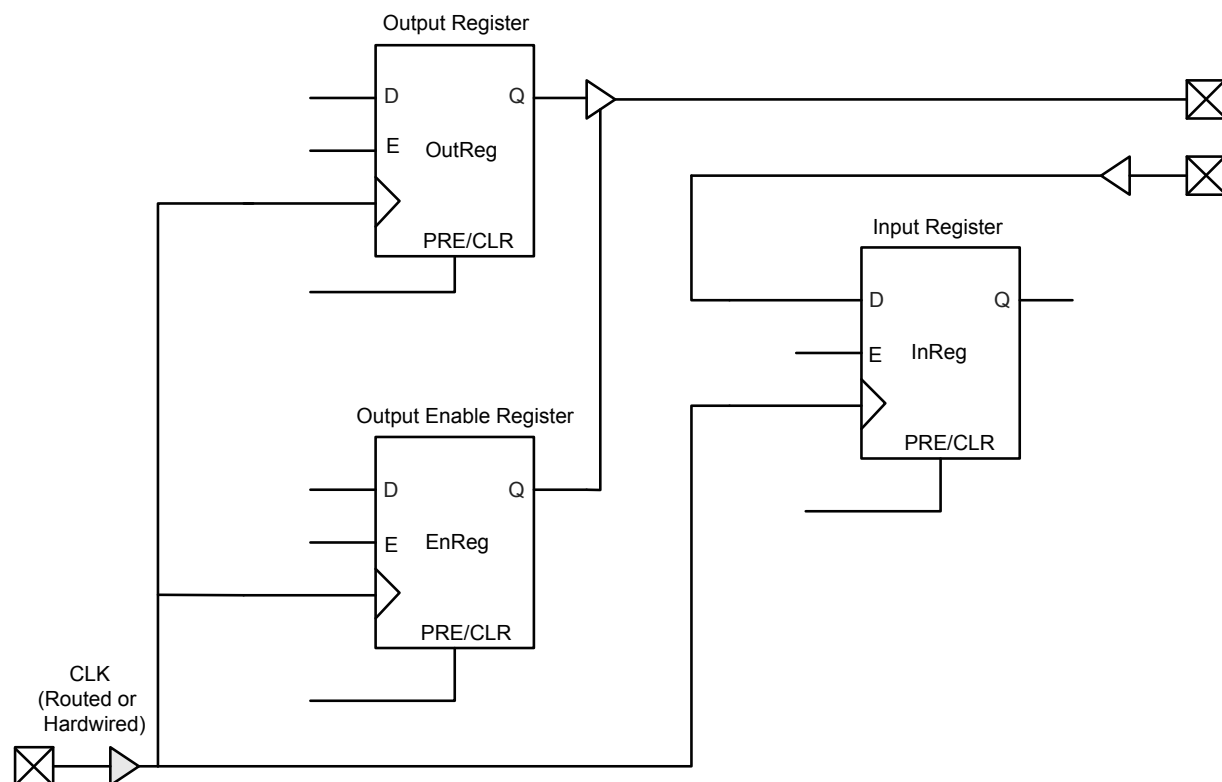


Figure 2-11 • Timing Model

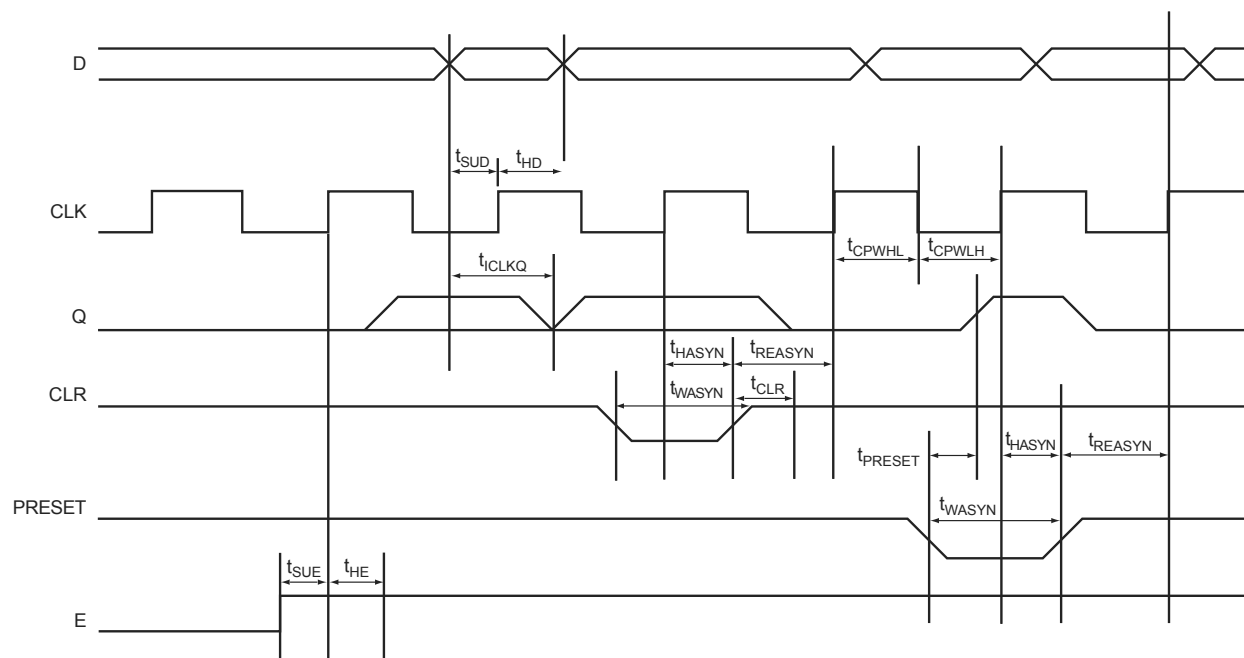


Figure 2-12 • Input Register Timing Characteristics

Table 2-36 • 3.3 V PCI-X I/O Module

Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		Units
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	
3.3 V PCI-X Output Module Timing								
t _{DP}	Input Buffer	1.57		1.79		2.10		ns
t _{PY}	Output Buffer	2.10		2.40		2.82		ns
t _{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low	1.61		1.62		1.63		ns
t _{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High	1.59		1.60		1.61		ns
t _{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z	2.65		3.02		3.55		ns
t _{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z	3.11		3.55		4.17		ns
t _{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register	0.67		0.77		0.90		ns
t _{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register	0.67		0.77		0.90		ns
t _{SUD}	Data Input Set-Up	0.23		0.27		0.31		ns
t _{SUE}	Enable Input Set-Up	0.26		0.30		0.35		ns
t _{HD}	Data Input Hold	0.00		0.00		0.00		ns
t _{HE}	Enable Input Hold	0.00		0.00		0.00		ns
t _{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t _{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t _{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t _{REASYN}	Asynchronous Recovery Time	0.13		0.15		0.17		ns
t _{HASYN}	Asynchronous Removal Time	0.00		0.00		0.00		ns
t _{CLR}	Asynchronous Clear-to-Q	0.23		0.27		0.31		ns
t _{PRESET}	Asynchronous Preset-to-Q	0.23		0.27		0.31		ns

SSTL3

Stub Series Terminated Logic for 3.3 V is a general-purpose 3.3 V memory bus standard (JESD8-8). The Axcelerator devices support both classes of this standard. This requires a differential amplifier input buffer and a push-pull output buffer.

Class I

Table 2-50 • DC Input and Output Levels

VIL		VIH		VOL	VOH	IOL	IOH
Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA
-0.3	VREF – 0.2	VREF + 0.2	3.6	VREF – 0.6	VREF + 0.6	8	–8

AC Loadings

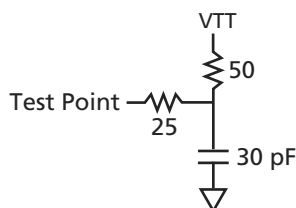


Figure 2-23 • AC Test Loads

Table 2-51 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C _{load} (pF)
VREF – 1.0	VREF + 1.0	VREF	1.50	30

Note: *Measuring Point = VTRIP

Timing Characteristics

Table 2-52 • 3.3 V SSTL3 Class I I/O Module

Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_j = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
3.3 V SSTL3 Class I I/O Module Timing								
t _{DP}	Input Buffer		1.78		2.03		2.39	ns
t _{PY}	Output Buffer		2.17		2.47		2.91	ns
t _{ICKLQ}	Clock-to-Q for the I/O input register		0.67		0.77		0.90	ns
t _{OCLKQ}	Clock-to-Q for the I/O output register and the I/O enable register		0.67		0.77		0.90	ns
t _{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t _{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t _{HD}	Data Input Hold		0.00		0.00		0.00	ns
t _{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t _{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t _{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t _{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t _{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t _{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t _{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t _{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

Table 2-57 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)
1.2 – 0.125	1.2 + 0.125	1.2

Note: * Measuring Point = VTRIP

Timing Characteristics

Table 2-58 • LVDS I/O Module

Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 2.3 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		Units
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	
LVDS Output Module Timing								
t _{DP}	Input Buffer	1.80		2.05		2.41		ns
t _{PY}	Output Buffer	2.32		2.64		3.11		ns
t _{CLKQ}	Clock-to-Q for the I/O input register	0.67		0.77		0.90		ns
t _{OCLKQ}	Clock-to-Q for the I/O output register and the I/O enable register	0.67		0.77		0.90		ns
t _{SUD}	Data Input Set-Up	0.23		0.27		0.31		ns
t _{SUE}	Enable Input Set-Up	0.26		0.30		0.35		ns
t _{HD}	Data Input Hold	0.00		0.00		0.00		ns
t _{HE}	Enable Input Hold	0.00		0.00		0.00		ns
t _{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t _{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t _{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t _{REASYN}	Asynchronous Recovery Time	0.13		0.15		0.17		ns
t _{HASYN}	Asynchronous Removal Time	0.00		0.00		0.00		ns
t _{CLR}	Asynchronous Clear-to-Q	0.23		0.27		0.31		ns
t _{PRESET}	Asynchronous Preset-to-Q	0.23		0.27		0.31		ns

LVPECL

Low-Voltage Positive Emitter-Coupled Logic (LVPECL) is another differential I/O standard. It requires that one data bit is carried through two signal lines. Like LVDS, two pins are needed. It also requires external resistor termination. The voltage swing between these two signal lines is approximately 850 mV.

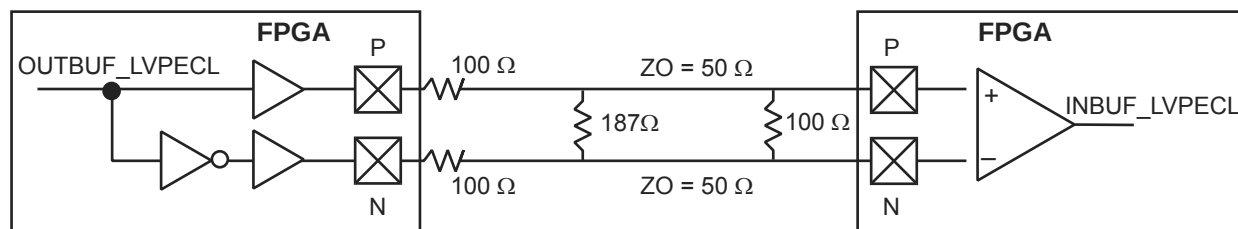


Figure 2-26 • LVPECL Board-Level Implementation

The LVPECL circuit is similar to the LVDS scheme. It requires four external resistors, three for the driver and one for the receiver. The values for the three driver resistors are different from that of LVDS since the output voltage levels are different. Please note that the VOH levels are 200 mV below the standard LVPECL levels.

Table 2-59 • DC Input and Output Levels

DC Parameter	Min.		Typ.		Max.		Units
	Min.	Max.	Min.	Max.	Min.	Max.	
VCCI	3		3.3		3.6		V
VOH	1.8	2.11	1.92	2.28	2.13	2.41	V
VOL	0.96	1.27	1.06	1.43	1.3	1.57	V
VIH	1.49	2.72	1.49	2.72	1.49	2.72	V
VIL	0.86	2.125	0.86	2.125	0.86	2.125	V
Differential Input Voltage	0.3		0.3		0.3		V

Table 2-60 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)
1.6 – 0.3	1.6 + 0.3	1.6

Note: * Measuring Point = VTRIP

Routed Clocks

The routed clock (CLK) is a low-skew network that can drive the clock inputs of all sequential modules in the device (logically equivalent to the HCLK), but has the added flexibility in that it can drive the S0 (Enable), S1, PSET, and CLR input of a register (R-cells and I/O registers) as well as any of the inputs of any C-cell in the device. This allows CLKs to be used not only as clocks, but also for other global signals or high fanout nets. All four CLKs are available everywhere on the chip.

Timing Characteristics

Table 2-75 • AX125 Routed Array Clock Networks

Worst-Case Commercial Conditions $V_{CCA} = 1.425\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$

		–2 Speed		–1 Speed		Std Speed		Units
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	
Routed Array Clock Networks								
t _{RCKL}	Input Low to High		3.08		3.50		4.12	ns
t _{RCKH}	Input High to Low		3.13		3.56		4.19	ns
t _{RPWH}	Minimum Pulse Width High	0.57		0.64		0.75		ns
t _{RPWL}	Minimum Pulse Width Low	0.52		0.59		0.69		ns
t _{RCKSW}	Maximum Skew		0.35		0.39		0.46	ns
t _{RP}	Minimum Period	1.15		1.31		1.54		ns
t _{RMAX}	Maximum Frequency		870		763		649	MHz

Table 2-76 • AX250 Routed Array Clock Networks

Worst-Case Commercial Conditions $V_{CCA} = 1.425\text{ V}$, $V_{CCI} = 3.0\text{ V}$, $T_J = 70^\circ\text{C}$

		–2 Speed		–1 Speed		Std Speed		Units
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	
Routed Array Clock Networks								
t _{RCKL}	Input Low to High	2.52		2.87		3.37		ns
t _{RCKH}	Input High to Low	2.59		2.95		3.47		ns
t _{RPWH}	Minimum Pulse Width High	0.57		0.64		0.75		ns
t _{RPWL}	Minimum Pulse Width Low	0.52		0.59		0.69		ns
t _{RCKSW}	Maximum Skew		0.35		0.39		0.46	ns
t _{RP}	Minimum Period	1.15		1.31		1.54		ns
t _{RMAX}	Maximum Frequency		870		763		649	MHz

single-ended, or voltage-referenced standard. The [H]CLKxN pad can only be used as a differential pair with [H]CLKxP.

The block marked “i Delay Match” is a fixed delay equal to that of the i divider. The “j Delay Match” block has the same function as its j divider counterpart.

Functional Description

Figure 2-48 on page 2-75 illustrates a block diagram of the PLL. The PLL contains two dividers, i and j, that allow frequency scaling of the clock signal:

- The i divider in the feedback path allows multiplication of the input clock by integer factors ranging from 1 to 64, and the resultant frequency is available at the output of the PLL block.
- The j divider divides the PLL output by integer factors ranging from 1 to 64, and the divided clock is available at CLK1.
- The two dividers together can implement any combination of multiplication and division up to a maximum frequency of 1 GHz on CLK1. Both the CLK1 and CLK2 outputs have a fixed 50/50 duty cycle.
- The output frequencies of the two clocks are given by the following formulas (f_{REF} is the reference clock frequency):

$$f_{CLK1} = f_{REF} * (DividerI) / (DividerJ)$$

EQ 4

$$f_{CLK2} = f_{REF} * (DividerI)$$

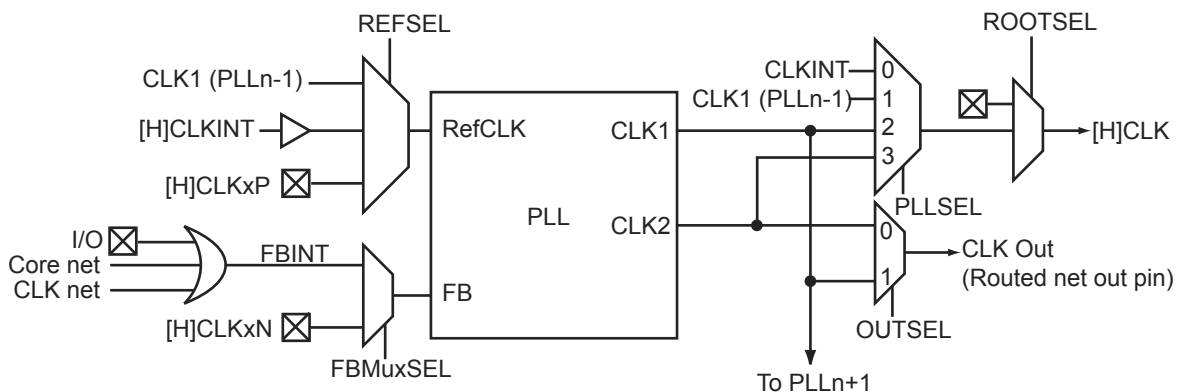
EQ 5

- CLK2 provides the PLL output directly—without division

The input and output frequency ranges are selected by LowFreq and Osc(2:0), respectively. These functions and their possible values are detailed in Table 2-80 on page 2-77.

The delay lines shown in Figure 2-48 on page 2-75 are programmable. The feedback clock path can be delayed (using the five DelayLine bits) relative to the reference clock (or vice versa) by up to 3.75 ns in increments of 250 ps. Table 2-80 on page 2-77 describes the usage of these bits. The delay increments are independent of frequency, so this results in phase changes that vary with frequency. The delay value is highly dependent on V_{CC} and the speed grade.

Figure 2-49 is a logical diagram of the various control signals to the PLL and shows how the PLL interfaces with the global and routing networks of the FPGA. Note that not all signals are user-accessible. These non-user-accessible signals are used by the place-and-route tool to control the configuration of the PLL. The user gains access to these control signals either based upon the connections built in the user's design or through the special macros (Table 2-84 on page 2-81) inserted into the design. For example, connecting the macro PLLOUT to CLK2 will control the OUTSEL signal.



Note: Not all signals are available to the user.

Figure 2-49 • PLL Logical Interface

Embedded Memory

The AX architecture provides extensive, high-speed memory resources to the user. Each 4,608 bit block of RAM contains its own embedded FIFO controller, allowing the user to configure each block as either RAM or FIFO.

To meet the needs of high performance designs, the memory blocks operate in synchronous mode for both read and write operations. However, the read and write clocks are completely independent, and each may operate up to and above 500 MHz.

No additional core logic resources are required to cascade the address and data buses when cascading different RAM blocks. Dedicated routing runs along each column of RAM to facilitate cascading.

The AX memory block includes dedicated FIFO control logic to generate internal addresses and external flag logic (FULL, EMPTY, AFULL, AEMPTY). Since read and write operations can occur asynchronously to one another, special control circuitry is included to prevent metastability, overflow, and underflow. A block diagram of the memory module is illustrated in Figure 2-57.

During RAM operation, read (RA) and write (WA) addresses are sourced by user logic and the FIFO controller is ignored. In FIFO mode, the internal addresses are generated by the FIFO controller and routed to the RAM array by internal MUXes. Enables with programmable polarity are provided to create upper address bits for cascading up to 16 memory blocks. When cascading memory blocks, the bussed signals WA, WD, WEN, RA, RD, and REN are internally linked to eliminate external routing congestion.

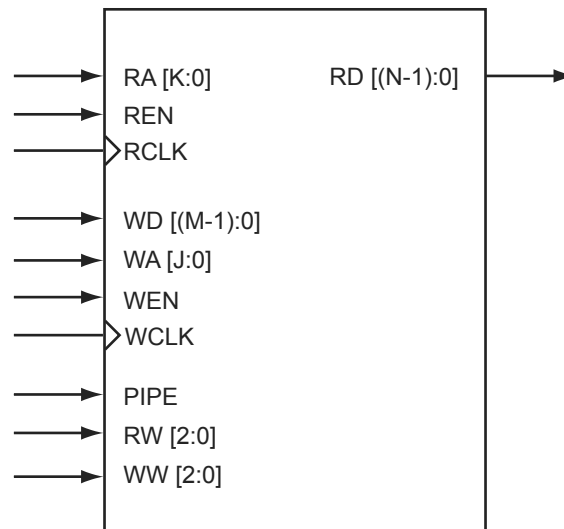


Figure 2-57 • Axcelerator Memory Module

Timing Characteristics

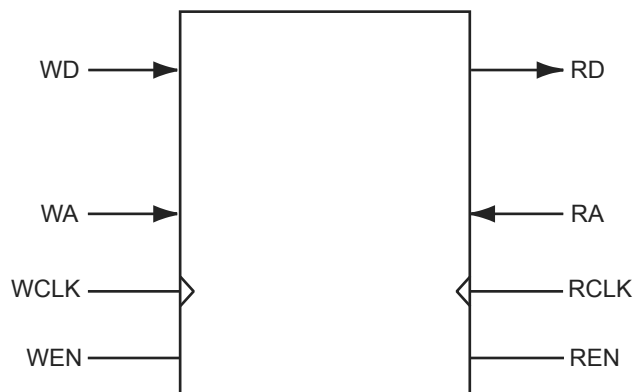


Figure 2-58 • SRAM Model

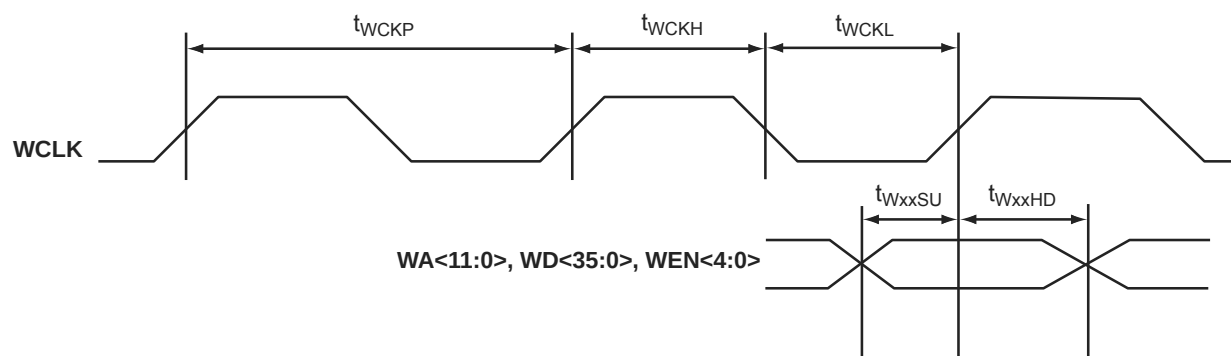


Figure 2-59 • RAM Write Timing Waveforms

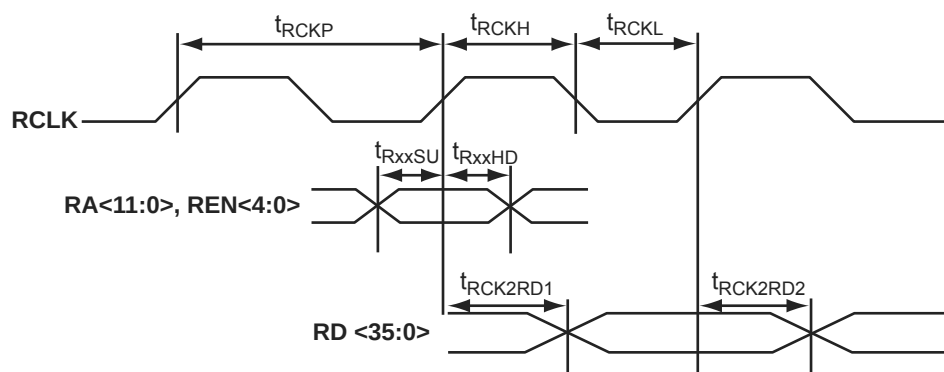


Figure 2-60 • RAM Read Timing Waveforms

Table 2-90 • Two RAM Blocks Cascaded
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
Write Mode								
t _{WDASU}	Write Data Setup vs. WCLK		1.39		1.59		1.87	ns
t _{WDAHD}	Write Data Hold vs. WCLK		0.00		0.00		0.00	ns
t _{WADSU}	Write Address Setup vs. WCLK		1.39		1.59		1.87	ns
t _{WADHD}	Write Address Hold vs. WCLK		0.00		0.00		0.00	ns
t _{WENSU}	Write Enable Setup vs. WCLK		1.39		1.59		1.87	ns
t _{WENHD}	Write Enable Hold vs. WCLK		0.00		0.00		0.00	ns
t _{WCKH}	WCLK Minimum High Pulse Width	0.75		0.75		0.75		ns
t _{WCLK}	WCLK Minimum Low Pulse Width	1.76		1.76		1.76		ns
t _{WCKP}	WCLK Minimum Period	2.51		2.51		2.51		ns
Read Mode								
t _{RADSU}	Read Address Setup vs. RCLK		1.71		1.94		2.28	ns
t _{RADHD}	Read Address Hold vs. RCLK		0.00		0.00		0.00	ns
t _{RENSU}	Read Enable Setup vs. RCLK		1.71		1.94		2.28	ns
t _{RENHD}	Read Enable Hold vs. RCLK		0.00		0.00		0.00	ns
t _{RCK2RD1}	RCLK-To-OUT (Pipelined)		1.43		1.63		1.92	ns
t _{RCK2RD2}	RCLK-To-OUT (Non-Pipelined)		2.26		2.58		3.03	ns
t _{RCLKH}	RCLK Minimum High Pulse Width	0.73		0.73		0.73		ns
t _{RCLKL}	RCLK Minimum Low Pulse Width	1.89		1.89		1.89		ns
t _{RCKP}	RCLK Minimum Period	2.62		2.62		2.62		ns

Note: Timing data for these two cascaded RAM blocks uses a depth of 8,192. For all other combinations, use Microsemi's timing software.

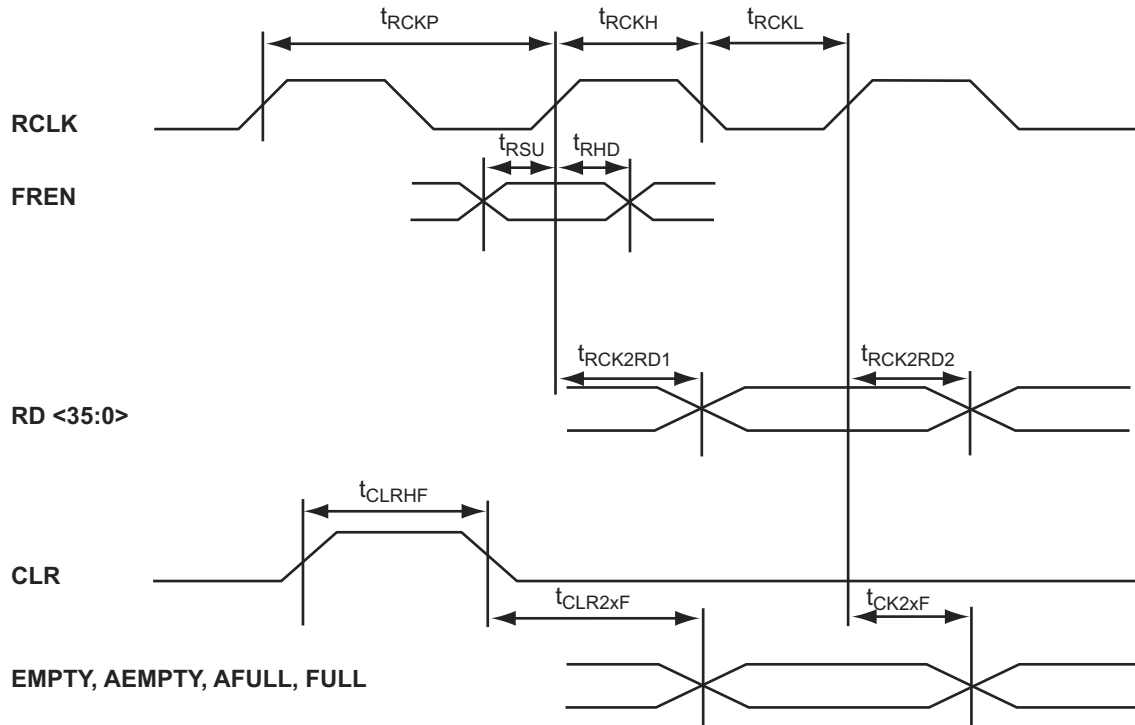


Figure 2-68 • FIFO Read Timing

FG256-Pin FBGA	
AX125 Function	Pin Number
VCCA	L10
VCCA	L7
VCCA	L8
VCCA	L9
VCCA	N3
VCCA	P14
VCCPLA	C7
VCCPLB	D6
VCCPLC	A10
VCCPLD	D10
VCCPLE	P10
VCCPLF	N11
VCCPLG	T7
VCCPLH	N7
VCCDA	A2
VCCDA	C13
VCCDA	D9
V _{CCDA}	H1
VCCDA	J15
VCCDA	N14
VCCDA	N8
VCCDA	P4
VCCIB0	E6
VCCIB0	E7
VCCIB0	E8
VCCIB1	E10
VCCIB1	E11
VCCIB1	E9
VCCIB2	F12
VCCIB2	G12
VCCIB2	H12
VCCIB3	J12
VCCIB3	K12
VCCIB3	L12
VCCIB4	M10

FG256-Pin FBGA	
AX125 Function	Pin Number
VCCIB4	M11
VCCIB4	M9
VCCIB5	M6
VCCIB5	M7
VCCIB5	M8
VCCIB6	J5
VCCIB6	K5
VCCIB6	L5
VCCIB7	F5
VCCIB7	G5
VCCIB7	H5
VCOMPLA	A7
VCOMPLB	D7
VCOMPLC	B9
VCOMPLD	D11
VCOMPLE	T10
VCOMPLF	N10
VCOMPLG	R8
VCOMPLH	N6
VPUMP	A14

FG484	
AX1000 Function	Pin Number
IO167PB5F15	AA12
IO169NB5F15	AA9
IO169PB5F15	AA10
IO170NB5F15	AB9
IO170PB5F15	AB10
IO171NB5F16	W8
IO171PB5F16	W9
IO172NB5F16	Y8
IO172PB5F16	Y9
IO173NB5F16	U8
IO173PB5F16	U9
IO174NB5F16	AA7
IO174PB5F16	AA8
IO175NB5F16	AB5
IO175PB5F16	AB6
IO176NB5F16	AA5
IO176PB5F16	AA6
IO177NB5F16	AA4
IO177PB5F16	AB4
IO178NB5F16	Y6
IO178PB5F16	Y7
IO179NB5F16	T7
IO179PB5F16	T8
IO180NB5F16	W6
IO180PB5F16	W7
IO181NB5F17	Y4
IO181PB5F17	Y5
IO184NB5F17	AB7
IO187NB5F17	V3
IO187PB5F17	W3
IO188NB5F17	V4
IO188PB5F17	W5
IO192NB5F17	V6
IO192PB5F17	V7
Bank 6	

FG484	
AX1000 Function	Pin Number
IO194NB6F18	V2
IO194PB6F18	W2
IO195NB6F18	U5
IO195PB6F18	T5
IO200NB6F18	T4
IO200PB6F18	U4
IO201NB6F18	P6
IO201PB6F18	R6
IO203NB6F19	U2
IO204NB6F19	T3
IO204PB6F19	U3
IO205NB6F19	P5
IO205PB6F19	R5
IO208NB6F19	V1
IO208PB6F19	W1
IO209NB6F19	P7
IO209PB6F19	R7
IO212NB6F19	P4
IO212PB6F19	R4
IO214NB6F20	P3
IO214PB6F20	R3
IO215NB6F20	M6
IO215PB6F20	N6
IO216NB6F20	R2
IO216PB6F20	T2
IO217NB6F20	T1
IO217PB6F20	U1
IO219NB6F20	M5
IO219PB6F20	N5
IO220NB6F20	P1
IO220PB6F20	R1
IO221NB6F20	N2
IO221PB6F20	P2
IO222NB6F20	M3
IO222PB6F20	N3

FG484	
AX1000 Function	Pin Number
IO223NB6F20	M7
IO223PB6F20	N7
IO224NB6F20	M4
IO224PB6F20	N4
Bank 7	
IO225NB7F21	M2
IO225PB7F21	N1
IO226NB7F21	K2
IO226PB7F21	K1
IO228NB7F21	L3
IO228PB7F21	L2
IO229NB7F21	K5
IO229PB7F21	L5
IO230NB7F21	H1
IO230PB7F21	J1
IO231NB7F21	H2
IO231PB7F21	J2
IO232NB7F21	K4
IO232PB7F21	K3
IO233NB7F21	K6
IO233PB7F21	L6
IO234NB7F21	F1
IO234PB7F21	G1
IO235NB7F21	F2
IO235PB7F21	G2
IO236NB7F22	H3
IO236PB7F22	J3
IO237NB7F22	K7
IO237PB7F22	L7
IO241NB7F22	H6
IO241PB7F22	J6
IO242NB7F22	H4
IO242PB7F22	J4
IO243NB7F22	H5
IO243PB7F22	J5

FG676	
AX1000 Function	Pin Number
GND	A8
GND	AC23
GND	AC4
GND	AD24
GND	AD3
GND	AE2
GND	AE25
GND	AF1
GND	AF13
GND	AF14
GND	AF19
GND	AF26
GND	AF8
GND	B2
GND	B25
GND	B26
GND	C24
GND	C3
GND	G20
GND	G7
GND	H1
GND	H19
GND	H26
GND	H8
GND	J18
GND	J9
GND	K10
GND	K11
GND	K12
GND	K13
GND	K14
GND	K15
GND	K16
GND	K17
GND	L10
GND	L11

FG676	
AX1000 Function	Pin Number
GND	L12
GND	L13
GND	L14
GND	L15
GND	L16
GND	L17
GND	M10
GND	M11
GND	M12
GND	M13
GND	M14
GND	M15
GND	M16
GND	M17
GND	N1
GND	N10
GND	N11
GND	N12
GND	N13
GND	N14
GND	N15
GND	N16
GND	N17
GND	N26
GND	P1
GND	P10
GND	P11
GND	P12
GND	P13
GND	P14
GND	P15
GND	P16
GND	P17
GND	P26
GND	R10
GND	R11

FG676	
AX1000 Function	Pin Number
GND	R12
GND	R13
GND	R14
GND	R15
GND	R16
GND	R17
GND	T10
GND	T11
GND	T12
GND	T13
GND	T14
GND	T15
GND	T16
GND	T17
GND	U10
GND	U11
GND	U12
GND	U13
GND	U14
GND	U15
GND	U16
GND	U17
GND	V18
GND	V9
GND	W1
GND	W19
GND	W26
GND	W8
GND	Y20
GND	Y7
GND/LP	C2
NC	A25
NC	AC13
NC	AC14
NC	AF2
NC	AF25

FG1152		FG1152		FG1152	
AX2000 Function	Pin Number	AX2000 Function	Pin Number	AX2000 Function	Pin Number
GND	AK12	GND	AN34	GND	D1
GND	AK17	GND	AN4	GND	D11
GND	AK18	GND	AN9	GND	D2
GND	AK23	GND	AP13	GND	D24
GND	AK30	GND	AP2	GND	D3
GND	AK5	GND	AP22	GND	D31
GND	AL1	GND	AP27	GND	D32
GND	AL11	GND	AP3	GND	D33
GND	AL2	GND	AP31	GND	D34
GND	AL24	GND	AP32	GND	D4
GND	AL3	GND	AP33	GND	E12
GND	AL31	GND	AP4	GND	E17
GND	AL32	GND	AP8	GND	E18
GND	AL33	GND	B1	GND	E23
GND	AL34	GND	B2	GND	E30
GND	AL4	GND	B26	GND	E5
GND	AM1	GND	B3	GND	F29
GND	AM10	GND	B31	GND	F30
GND	AM15	GND	B32	GND	F6
GND	AM2	GND	B33	GND	G28
GND	AM20	GND	B34	GND	G7
GND	AM25	GND	B4	GND	H1
GND	AM3	GND	B9	GND	H34
GND	AM31	GND	C1	GND	J2
GND	AM32	GND	C10	GND	J33
GND	AM33	GND	C15	GND	K3
GND	AM34	GND	C2	GND	K32
GND	AM4	GND	C20	GND	L11
GND	AN1	GND	C25	GND	L24
GND	AN2	GND	C3	GND	L31
GND	AN26	GND	C31	GND	L4
GND	AN3	GND	C32	GND	M12
GND	AN31	GND	C33	GND	M23
GND	AN32	GND	C34	GND	M30
GND	AN33	GND	C4	GND	M5

CQ352	
AX2000 Function	Pin Number
IO182PB4F17	171
IO183NB4F17	166
IO183PB4F17	167
IO184NB4F17	164
IO184PB4F17	165
IO185NB4F17	160
IO185PB4F17	161
IO190NB4F17	158
IO190PB4F17	159
IO191NB4F17	154
IO191PB4F17	155
IO192NB4F17	152
IO192PB4F17	153
IO207NB4F19	146
IO207PB4F19	147
IO212NB4F19/CLKEN	142
IO212PB4F19/CLKEP	143
IO213NB4F19/CLKFN	136
IO213PB4F19/CLKFP	137
Bank 5	
IO214NB5F20/CLKGN	128
IO214PB5F20/CLKGP	129
IO215NB5F20/CLKHN	122
IO215PB5F20/CLKHP	123
IO217NB5F20	118
IO217PB5F20	119
IO236NB5F22	110
IO236PB5F22	111
IO237NB5F22	112
IO237PB5F22	113
IO238NB5F22	104
IO238PB5F22	105
IO239NB5F22	106
IO239PB5F22	107
IO240NB5F22	100

CQ352	
AX2000 Function	Pin Number
IO240PB5F22	101
IO242NB5F22	94
IO242PB5F22	95
IO243NB5F22	98
IO243PB5F22	99
IO244NB5F22	92
IO244PB5F22	93
Bank 6	
IO257PB6F24	86
IO258NB6F24	84
IO258PB6F24	85
IO261NB6F24	82
IO261PB6F24	83
IO262NB6F24	78
IO262PB6F24	79
IO265NB6F24	76
IO265PB6F24	77
IO279NB6F26	72
IO279PB6F26	73
IO280NB6F26	70
IO280PB6F26	71
IO281NB6F26	66
IO281PB6F26	67
IO282NB6F26	64
IO282PB6F26	65
IO284NB6F26	60
IO284PB6F26	61
IO285NB6F26	58
IO285PB6F26	59
IO286NB6F26	54
IO286PB6F26	55
IO287NB6F26	52
IO287PB6F26	53
IO294NB6F27	48
IO294PB6F27	49

CQ352	
AX2000 Function	Pin Number
IO296NB6F27	46
IO296PB6F27	47
Bank 7	
IO300NB7F28	42
IO300PB7F28	43
IO303NB7F28	40
IO303PB7F28	41
IO310NB7F29	34
IO310PB7F29	35
IO311NB7F29	36
IO311PB7F29	37
IO312NB7F29	28
IO312PB7F29	29
IO315NB7F29	30
IO315PB7F29	31
IO316NB7F29	22
IO316PB7F29	23
IO317NB7F29	24
IO317PB7F29	25
IO318NB7F29	18
IO318PB7F29	19
IO320NB7F29	16
IO320PB7F29	17
IO334NB7F31	10
IO334PB7F31	11
IO335NB7F31	12
IO335PB7F31	13
IO338NB7F31	6
IO338PB7F31	7
IO341NB7F31	4
IO341PB7F31	5
Dedicated I/O	
GND	1
GND	9
GND	15

Revision	Changes	Page
Revision 8 (continued)	The following changes were made in the "FG676"(AX500) section: AE2, AE25 Change from NC to GND. AF2, AF25 Changed from GND to NC AB4, AF24, C1, C26 Changed from V_{CCDA} to V_{CCA} AD15 Change from V_{CCDA} to V_{COMPLE} AD17 Changed from V_{COMPLE} to V_{CCDA}	3-37
	In the "FG896" (AX2000) section, the AK28 changed from VCCIB5 to VCCIB4.	3-52
	The "CQ352" and "CG624" sections are new.	3-98, 3-115
Revision 7 (Advance v1.6)	All I/O FIFO capability was removed.	n/a
	Table 1 was updated.	i
	Figure 1-9 was updated.	1-7
	Figure 2-5 was updated.	2-16
	The "Using an I/O Register" section was updated.	2-16
	The AX250 and AX1000 descriptions were added to the "FG484" section.	3-21
Revision 6 (Advance v1.5)	Table 2-3 was updated.	2-2
	Figure 2-1 was updated.	2-8
	Figure 2-48 was updated.	2-75
	Figure 2-52 was updated.	2-82
Revision 5 (Advance v1.4)	In the "PQ208" table, pin 196 was missing, but it has been added in this version with a function of GND.	3-84
	The following pins in the "FG484" table for AX500 were changed: Pin G7 is GND/LP Pins AB8, C10, C11, C14, AB16 are NC.	3-21
	The "FG676" table was updated.	3-37
Revision 4 (Advance v1.3)	The "Device Resources" section was updated for the CS180.	ii
	The "Programmable Interconnect Element" and Figure 1-2 are new.	1-1 and 1-2
	The "CS180" table is new.	3-1
	The "PQ208" tables for the AX500 were updated. The following pins were not defined in the previous version: GND 21 IO106PB5F10/CLKHP 71 GND 136	3-84
Revision 3 (Advance v1.2)	Table 1, "Ordering Information", "Device Resources", and the Product Plan table were updated.	i, ii
	The following figures and tables were updated:	
	Figure 1-3	1-2
	Figure 1-8 (new)	1-6
	Table 2-3	2-2
	Figure 2-2	2-9
	Table 2-8	2-12
	Figure 2-11	2-23
	The "Design Environment" section was updated.	1-7
	The "Package Thermal Characteristics" was updated.	2-6